



04-29-02

2812

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Hua Ji  
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench  
Application No.: 10/080,468 Filing Date: February 22, 2002  
Examiner: Unknown Group Art Unit: Unknown  
Docket No.: M-12589 US

#3 7-29-02  
ext 10San Jose, California  
April 26, 2002COMMISSIONER FOR PATENTS  
Washington, D.C. 20231INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR § 1.97(b)RECEIVED  
MAY -1 2002  
TECHNOLOGY CENTER 2800

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, the documents listed on the accompanying form PTO-1449 are called to the attention of the Examiner for the above patent application. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

EXPRESS MAIL LABEL NO:

EL 922457185 US

Respectfully submitted,

Greg J. Michelson  
Attorney for Applicant(s)  
Reg. No. 44,940LAW OFFICES OF  
SKJERVEN MORRILL  
MacPHERSON LLP25 METRO DRIVE  
SUITE 700  
SAN JOSE, CA 95110  
(408) 453-9200  
FAX (408) 453-7979